



RF Power Field Effect Transistors

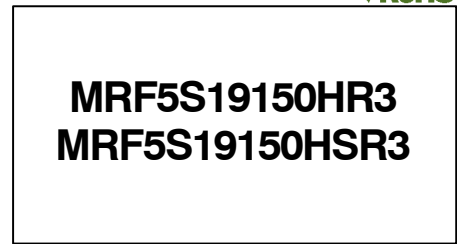
N-Channel Enhancement-Mode Lateral MOSFETs

Designed for PCN and PCS base station applications at frequencies from 1900 to 2000 MHz. Suitable for TDMA, CDMA and multicarrier amplifier applications.

- Typical 2-Carrier N-CDMA Performance for $V_{DD} = 28$ Volts, $I_{DQ} = 1400$ mA, Avg., $P_{out} = 32$ Watts Avg., Full Frequency Band, IS-95 CDMA (Pilot, Sync, Paging, Traffic Codes 8 Through 13) Channel Bandwidth = 1.2288 MHz. PAR = 9.8 dB @ 0.01% Probability on CCDF.
 - Power Gain — 14 dB
 - Drain Efficiency — 26%
 - IM3 @ 2.5 MHz Offset — -36.5 dBc in 1.2288 MHz Bandwidth
 - ACPR @ 885 kHz Offset — -50 dB in 30 kHz Bandwidth
- Capable of Handling 5:1 VSWR, @ 28 Vdc, 1960 MHz, 100 Watts CW Output Power

Features

- Characterized with Series Equivalent Large-Signal Impedance Parameters
- Internally Matched for Ease of Use
- Qualified Up to a Maximum of 32 V Operation
- Integrated ESD Protection
- Lower Thermal Resistance Package
- Low Gold Plating Thickness on Leads, 40 μ ” Nominal.
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.



**1930-1990 MHz, 32 W AVG., 28 V
 2 x N-CDMA
 LATERAL N-CHANNEL
 RF POWER MOSFETs**

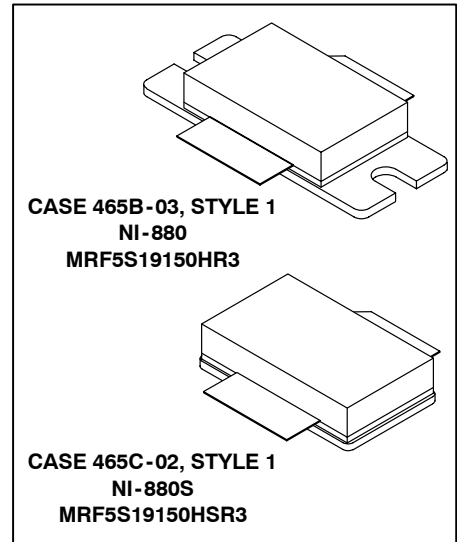


Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25 $^\circ\text{C}$	P_D	427 2.44	W W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to +150	$^\circ\text{C}$
Case Operating Temperature	T_C	150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$
CW Operation @ $T_C = 25^\circ\text{C}$ Derate above 25 $^\circ\text{C}$	CW	120 0.76	W W/ $^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (1,2)	Unit
Thermal Resistance, Junction to Case Case Temperature 80 $^\circ\text{C}$, 100 W CW Case Temperature 75 $^\circ\text{C}$, 32 W CW	$R_{\theta JC}$	0.41 0.44	$^\circ\text{C}/\text{W}$

1. MTF calculator available at <http://www.freescale.com/rf>. Select Tools/Software/Application Software/Calculators to access the MTF calculators by product.
2. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.freescale.com/rf>. Select Documentation/Application Notes - AN1955.

Table 3. ESD Protection Characteristics

Test Conditions	Class
Human Body Model	1 (Minimum)
Machine Model	M3 (Minimum)
Charge Device Model	C7 (Minimum)

Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 65\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc

On Characteristics

Gate Threshold Voltage ($V_{DS} = 10\text{ Vdc}$, $I_D = 360\ \mu\text{Adc}$)	$V_{GS(th)}$	2.5	2.8	3.5	Vdc
Gate Quiescent Voltage ($V_{DS} = 28\text{ Vdc}$, $I_D = 1400\text{ mAdc}$)	$V_{GS(Q)}$	—	3.8	—	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 3.6\text{ Adc}$)	$V_{DS(on)}$	—	0.24	—	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 3.6\text{ Adc}$)	g_{fs}	—	9	—	S

Dynamic Characteristics

Reverse Transfer Capacitance ⁽¹⁾ ($V_{DS} = 28\text{ Vdc}$, $V_{GS} = 0$, $f = 1\text{ MHz}$)	C_{rss}	—	3.1	—	pF
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Functional Tests (In Freescale Test Fixture, 50 ohm system) $V_{DD} = 28\text{ Vdc}$, $I_{DQ} = 1400\text{ mA}$, $P_{out} = 32\text{ W Avg.}$, $f_1 = 1930\text{ MHz}$, $f_2 = 1932.5\text{ MHz}$ and $f_1 = 1987.5\text{ MHz}$, $f_2 = 1990\text{ MHz}$, 2-Carrier N-CDMA, 1.2288 MHz Channel Bandwidth Carriers. ACPR measured in 30 kHz Channel Bandwidth @ $\pm 885\text{ kHz}$ Offset. IM3 measured in 1.2288 MHz Channel Bandwidth @ $\pm 2.5\text{ MHz}$ Offset. PAR = 9.8 dB @ 0.01% Probability on CCDF.

Power Gain	G_{ps}	13	14	—	dB
Drain Efficiency	η_D	24	26	—	%
Intermodulation Distortion	IM3	—	-36.5	-35	dBc
Adjacent Channel Power Ratio	ACPR	—	-50	-48	dBc
Input Return Loss	IRL	—	-17	-9	dB

1. Part internally matched both on input and output.

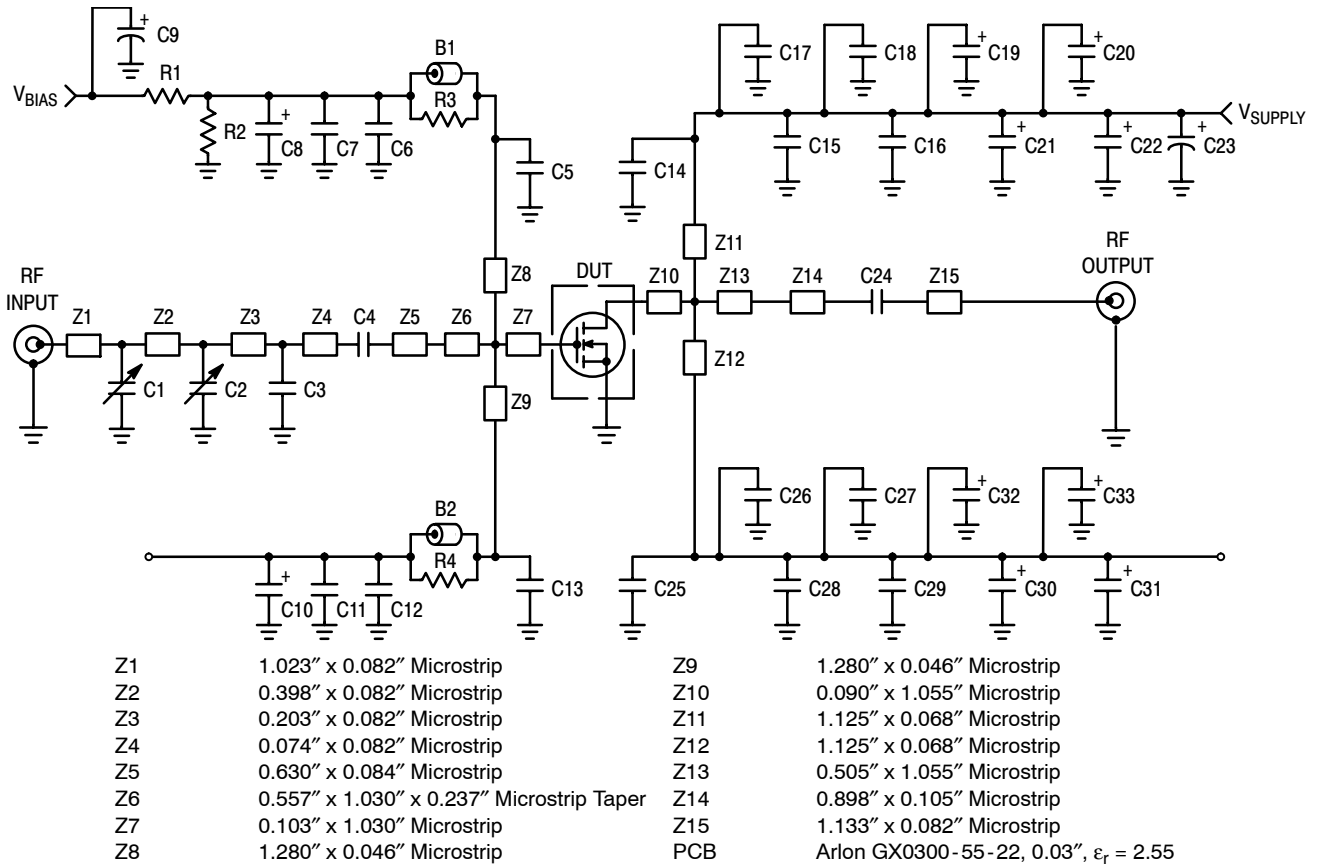
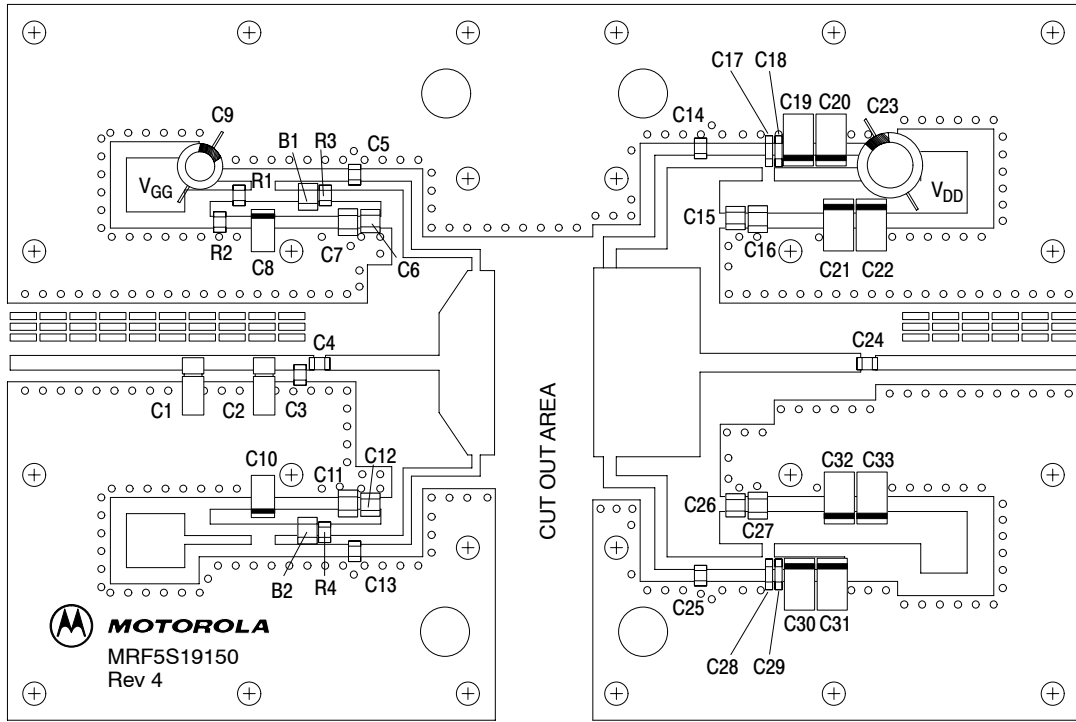


Figure 1. MRF5S19150HR3(SR3) Test Circuit Schematic

Table 5. MRF5S19150HR3(SR3) Test Circuit Component Designations and Values

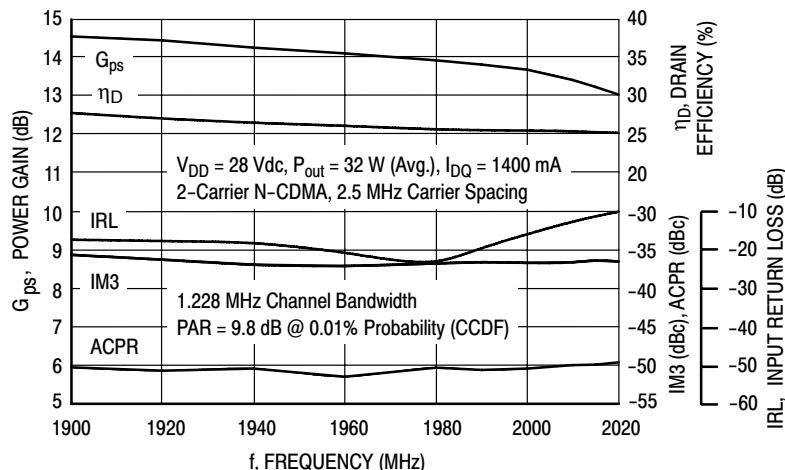
Part	Description
B1, B2	Short RF Beads
C1, C2	0.6 – 4.5 Variable Capacitors, Gigatrim
C3	0.8 pF Chip Capacitor
C4, C5, C13, C14, C24, C25	9.1 pF Chip Capacitors
C8, C10	1.0 μ F, 50 V SMT Tantalum Capacitors
C6, C12, C16, C17, C18, C27, C28, C29	0.1 μ F Chip Capacitors
C7, C11, C15, C26	1000 pF Chip Capacitors
C9	100 μ F, 50 V Electrolytic Capacitor
C23	470 μ F, 63 V Electrolytic Capacitor
C19, C20, C21, C22, C30, C31, C32, C33	22 μ F, 35 V Tantalum Capacitors
R1	1 k Ω Chip Resistor
R2	560 k Ω Chip Resistor
R3, R4	12 Ω Chip Resistors



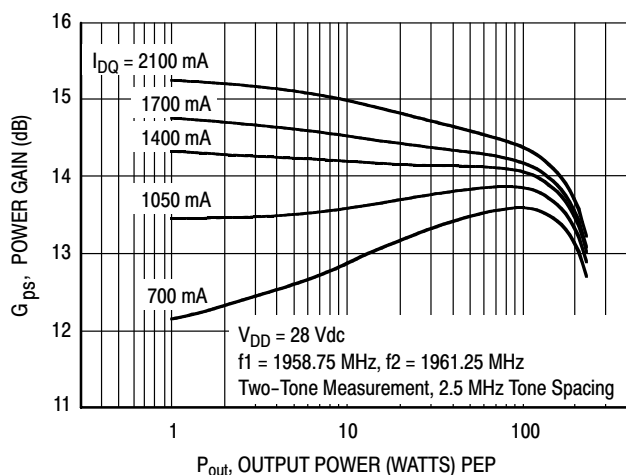
Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MRF5S19150HR3(SR3) Test Circuit Component Layout

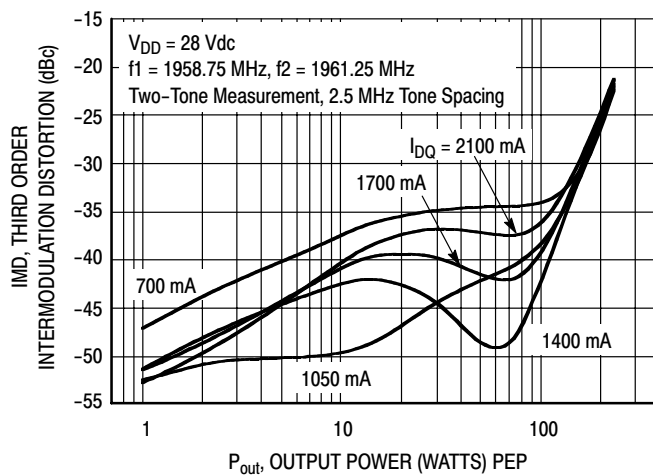
TYPICAL CHARACTERISTICS



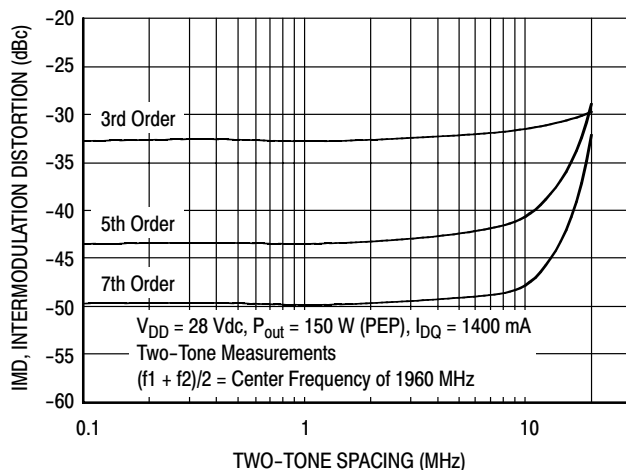
**Figure 3. 2-Carrier N-CDMA Broadband Performance
@ P_{out} = 32 Watts Avg.**



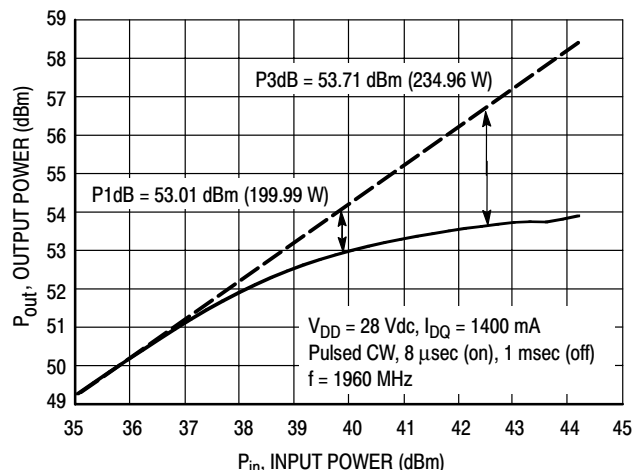
**Figure 4. Two-Tone Power Gain versus
Output Power**



**Figure 5. Third Order Intermodulation versus
Output Power**



**Figure 6. Intermodulation Distortion Products
versus Tone Spacing**



**Figure 7. Pulse CW Output Power versus
Input Power**

TYPICAL CHARACTERISTICS

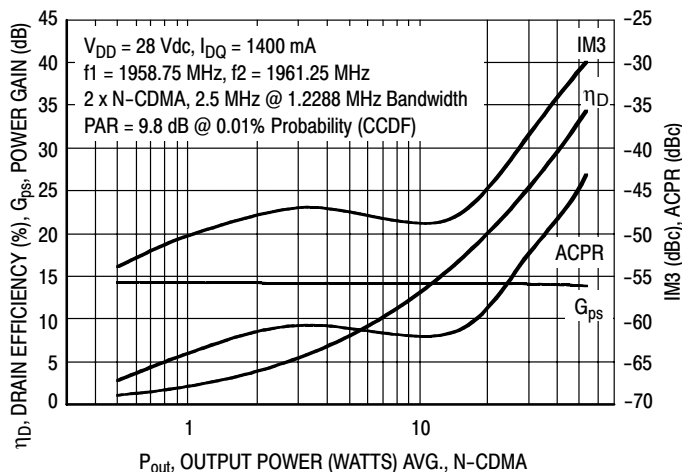
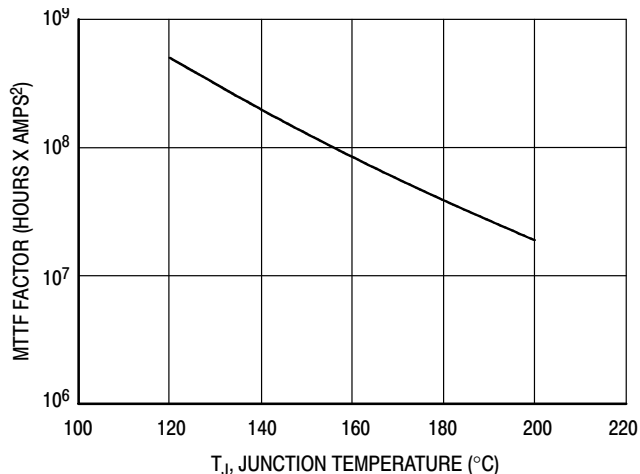


Figure 8. 2-Carrier N-CDMA ACPR, IM3, Power Gain, Drain Efficiency versus Output Power



This above graph displays calculated MTTF in hours x ampere² drain current. Life tests at elevated temperatures have correlated to better than $\pm 10\%$ of the theoretical prediction for metal failure. Divide MTTF factor by I_D^2 for MTTF in a particular application.

Figure 9. MTTF Factor versus Junction Temperature

N-CDMA TEST SIGNAL

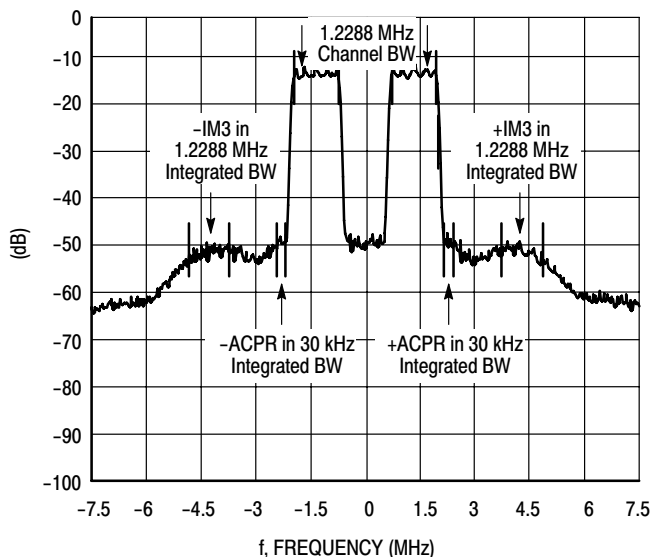
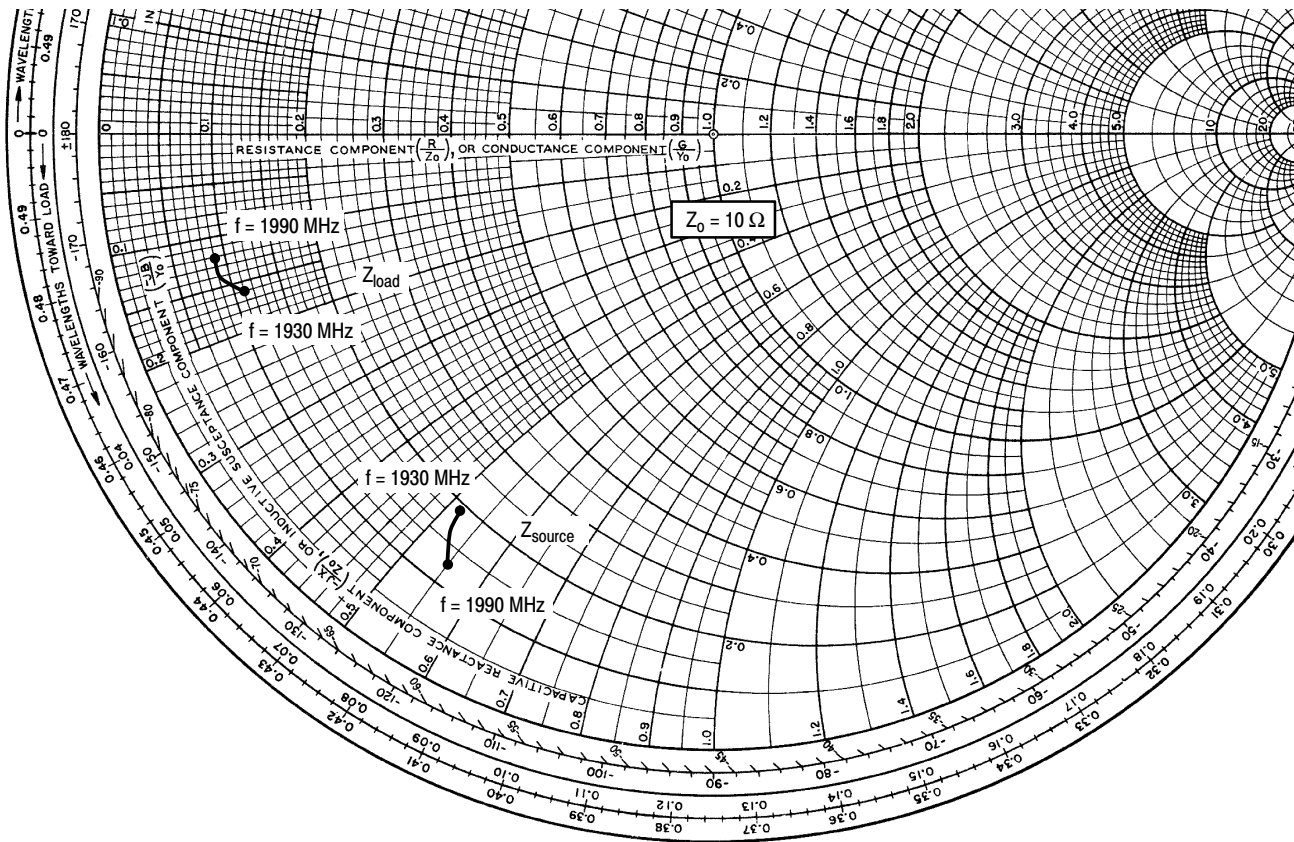


Figure 10. 2-Carrier N-CDMA Spectrum



$V_{DD} = 28\text{ V}$, $I_{DQ} = 1400\text{ mA}$, $P_{out} = 32\text{ W Avg.}$

f MHz	Z_{source} Ω	Z_{load} Ω
1930	$1.89 - j5.24$	$1.06 - j1.58$
1960	$1.64 - j5.29$	$0.88 - j1.37$
1990	$1.3 - j5.49$	$0.90 - j1.21$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

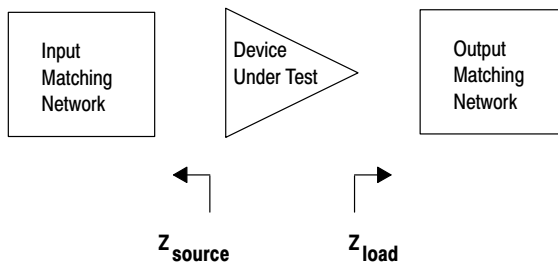


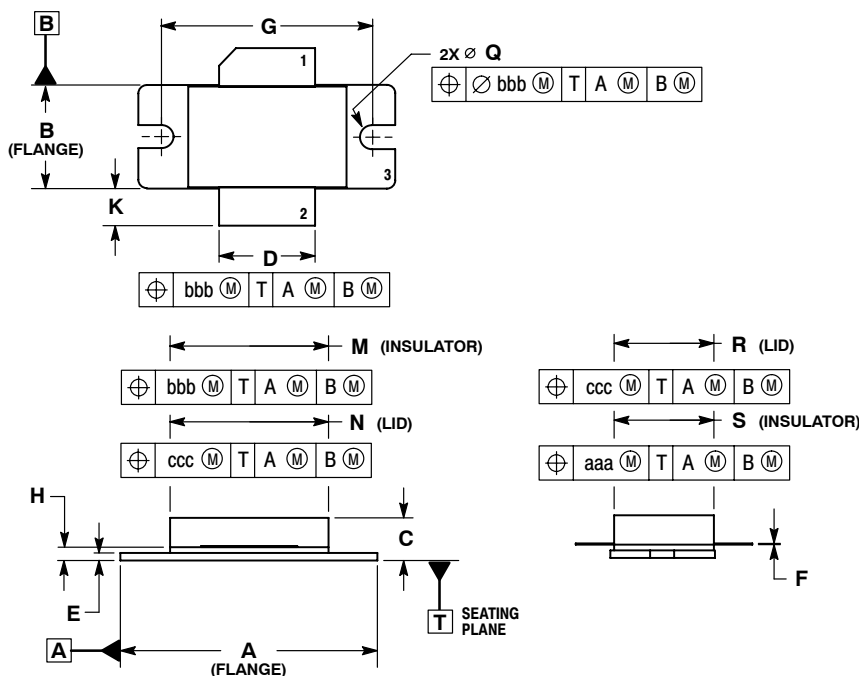
Figure 11. Series Equivalent Source and Load Impedance

NOTES

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PACKAGE DIMENSIONS

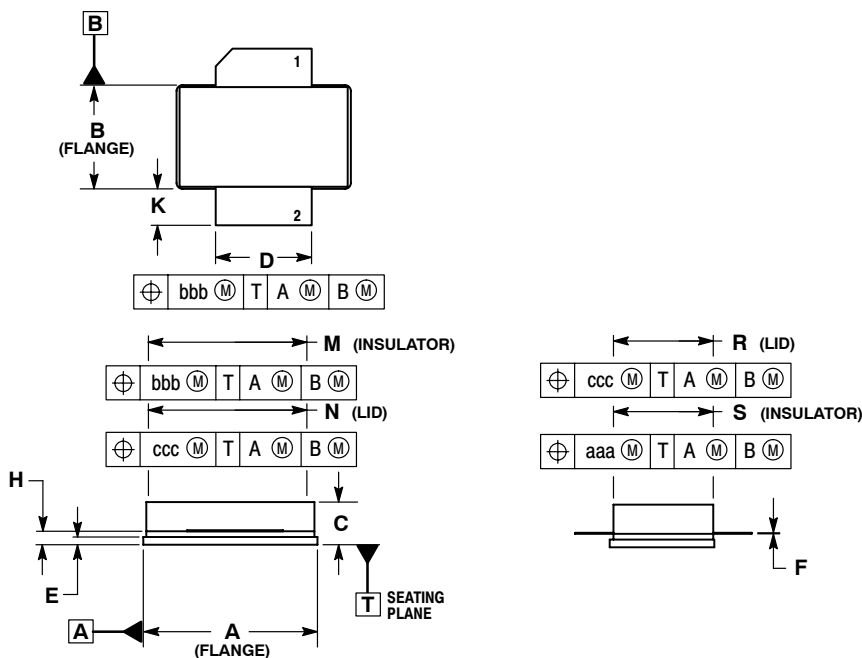


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
 4. DELETED

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.535	0.545	13.6	13.8
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
Q	∅.118	∅.138	∅3.00	∅3.51
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

- STYLE 1:
 PIN 1. DRAIN
 2. GATE
 3. SOURCE

**CASE 465B-03
 ISSUE D
 NI-880
 MRF5S19150HR3**



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.905	0.915	22.99	23.24
B	0.535	0.545	13.60	13.80
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
H	0.057	0.067	1.45	1.70
K	0.170	0.210	4.32	5.33
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

- STYLE 1:
 PIN 1. DRAIN
 2. GATE
 3. SOURCE

**CASE 465C-02
 ISSUE D
 NI-880S
 MRF5S19150HSR3**

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